ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR DEVICE ASSEMBLIES INCLUDING FACE-TO-FACE SEMICONDUCTOR DICE, SYSTEMS INCLUDING SUCH ASSEMBLIES, AND METHODS FOR FABRICATING SUCH ASSEMBLIES

Semiconductor device assemblies include at least first and second semiconductor dice disposed in a face-to-face configuration. At least some of a plurality of conductive structures are electrically and structurally coupled to a bond pad of the first semiconductor die and a bond pad of the second semiconductor die. A first end of each of a plurality of laterally extending conductive elements may be structurally and electrically coupled to a conductive terminal of a substrate, and a second end of each laterally extending conductive element is structurally and electrically coupled to at least one of a bond pad of the first semiconductor die, a bond pad of the second semiconductor die, and a conductive structure. Methods include the fabrication of such assemblies. Electronic systems include at least one electronic signal processing device, at least one input or output device, and at least one memory device including such a semiconductor device assembly.

[FIG. 3]